

## AMENDMENTS TO THE SPECIFICATION

Please amend the paragraph spanning pages 7 and 8 as follows:

In accordance with certain aspects of the present invention, a modified solder bump pattern can be used to fully isolate an unused or non-functional circuit as illustrated in **FIG. 5**. Locations of the circuitry 108, 112, 116 and 120 are again depicted by broken lines and the circuit designation numbers. In this illustration, circuit [[108]] 112 is to be effectively disabled by virtue of not connecting the power supply voltage and ground. These connections, along with all other connections in this illustration are omitted by use of a different solder mask than that described in conjunction with **FIG. 4**. The solder mask used to deposit solder to die 100 in **FIG. 5** has no provision for permitting any solder to be applied to interconnect any of the circuitry of circuit [[108]] 112. Thus, no power or ground connections are made to circuit [[108]] 112 and the circuit is isolated and disabled from the remaining circuitry of die 100. All connections are made to circuit [[112]] 108 so that, in the example embodiment, a single microprocessor core [[112]] 108 is active in the die soldered according to **FIG. 5**. The substrate used in connection with this solder bump pattern may be identical to that used in connection with **FIG. 4** and incorporate a complete set of solder pads, or may omit the solder pads associated with circuit [[112]] 108 without departing from the invention.

Please amend the first full paragraph on page 8 as follows:

**FIG. 6** illustrates another exemplary solder bump arrangement in which circuit [[112]] 108 is disabled and circuit [[108]] 112 is enabled. Again, locations of the circuitry 108, 112, 116 and 120 are depicted by broken lines and the circuit designation numbers. In this example, circuit [[112]] 108 is disabled using a third solder mask or other mechanism to selectively deposit solder on the die. Thus, in this embodiment, power and other connections are omitted to circuit [[112]] 108 to effectively disable the circuit. In this illustration, however, solder pad [[140]] 130 is still connected in order to make a stable ground substrate connection over the unused circuit [[112]] 108. Again, the substrate used in connection with this solder bump pattern may be identical to that used in connection with **FIG. 4** and incorporate a complete set of solder pads, or may

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omit the solder pads associated with circuit [[112]] 108 (except for the ground pad [[140]] 130) without departing from the invention.